

Application Note DA9063L Schematic Checklist AN-PM-107

Abstract

Optimizing the schematic for DA9063L ensures correct and efficient operation of the PMIC and the system. This is achieved by selecting appropriate external passive components, and appropriate configuration of the PMIC OTP.

AN-PM-107



DA9063L Schematic Checklist

Contents

| | stract | |
|----|-----------------------|---|
| Co | ntents | 2 |
| 1 | Terms and Definitions | 3 |
| 2 | References | 3 |
| 3 | Introduction | 4 |
| 4 | Schematic Checklist | 4 |
| 5 | Further Assistance | 8 |
| Re | vision History | 9 |

AN-PM-107



DA9063L Schematic Checklist

1 Terms and Definitions

| PMIC | Power Management Integrated Circuit |
|--------|-------------------------------------|
| DA906x | DA9061, DA9062, DA9063, DA9063L |
| GUI | Graphical User Interface |
| OTP | One-Time Programmable (memory) |
| RTC | Real-Time Clock |
| SoC | System on (a) Chip |
| PMIC | Power Management Integrated Circuit |
| GPIO | General Purpose Input / Output |

2 References

[1] DA9063L, Datasheet, Dialog Semiconductor

Application Note



3 Introduction

DA9063L is a high-current system PMIC suitable for dual- and quad-core processors used in smartphones, tablets, ultra-books, and other handheld and automotive applications that require up to 12 A core processor supply.

This checklist is intended to help a hardware designer identify common errors that can arise in schematics containing the DA9063L. The checklist is only a reference to common errors, and is not a substitute for rigorous system development and an understanding of the PMIC behavior as described in the DA9063L datasheet [1].

4 Schematic Checklist

Table 1: Checklist

| General | Comments | | |
|-------------------------------------|---|------------------|----------|
| Design name | | | |
| Schematic version | | | |
| Review date | | | |
| OTP variant | Notes | Checked (Y/N) | Comments |
| Which OTP variant is being used? | This can provide useful background for the review. | | |
| OTP version number | | | |
| Core Operation | | | |
| V _{SYS} | 2.8 V to 5.5 V | | |
| Vddio | 1.2 V to 3.6 V | | |
| VSYS capacitor | 1 μF | | |
| IREF resistor | 200 kΩ. Must be ≤ 1 % tolerance. | | |
| VREF capacitor | 220 nF | | |
| VLNREF | 220 nF | | |
| VBBAT capacitor | No connect. | | |
| VDDCORE capacitor | 2.2 μF | | |
| V_CP | 47 nF | | |
| Crystal | The RTC requires an external crystal of 32.768 kHz and load capacitors. | | |
| XTAL_IN and XTAL_OUT | If a crystal or an external 32 kHz source is not required, then both pins should be grounded. | | |

AN-PM-107



DA9063L Schematic Checklist

| Core operation | ore operation Notes | | Comments |
|--|---|--|----------|
| nRESET timing The nRESET timer control can be set in the GUI. RESET_EVENT sets the timer start reference and RESET_TIMER sets the delay until nRESET is released. Make sure nRESET is active until all important rails have turned on. | | | |
| nRESET pin | Register control IRQ_TYPE determines if the pin is push-pull or open-drain. Check that an external pull-up is present if open-drain. | | |
| nONKEY | nONKEY should be either pulled high to V _{SYS} or tied to V _{SYS} , and never left floating. | | |
| nOFF | nOFF should be either pulled high to V _{SYS} or tied to V _{SYS} , and never left floating. | | |
| nSHUTDOWN | nSHUTDOWN should be either pulled high to V _{SYS} or tied to V _{SYS} , and never left floating. | | |
| CHG_WAKE | Wake-up signal from companion charger which triggers a start-up and is a temporary supply voltage for the PMIC (VBUS_PROT in case of an inserted supply until the charger buck provides power to VSYS) Should not be left floating. Pull down to ground, via 10 k Ω . | | |
| ТР | TP should not be left floating. Pull down to ground, via 10 k Ω . Ideally, a test-point will be provided for system debug. | | |
| LDOs | | | |
| LDO input voltages | 2.8 V to 5.5 V If supplied by a buck, the minimum voltage is 1.5 V. | | |
| LDO input capacitor | Note 1 | | |
| LDO output capacitor | 2.2 μF | | |
| LDO output voltage | LDO3: 0.9 V to 3.44 V LDO7/8/11: 0.9 V to 3.6 V LDO9: 0.95 V to 3.6 V | | |
| LDO output current | LDO3/7/8/9: 200 mA LDO11: 300 mA | | |
| DVC_ <x> register controlIf VDLO<x>_SEL_A and VDLO<x>_SEL_B have different voltages and only one specific voltage is desired, then the regulator needs to be set correctly.</x></x></x> | | | |

Application Note





| Bucks | Notes | | Checked (Y/N) | Comments |
|--|---|---|------------------|----------|
| Buck supply voltage | 2.8 V to 5.5 V | | | |
| Input capacitors | Note 2, Note 3 | | | |
| Buck output current Buck o | | | | |
| Buck: current limit register settings ILIM | Controlled with B <x>_ILIM register. BUCKCORE1 and BUCKCORE2: • Full Current Mode: 1000 mA to 4000 mA • Half Current Mode: 500 mA to 2000 mA BUCKPRO: 500 mA to 2000 mA BUCKPERI: 1500 mA to 3000 mA BUCKMEM: 1500 mA to 3000 mA BUCKIO: 1500 mA to 3000 mA</x> | | | |
| Minimum ISAT values required at current limits | Current limit: 3400 mA 2800 mA 2100 mA 1700 mA | ISAT: 3800 mA 3100 mA 2400 mA 1700 mA | | |
| CORE1 / CORE2 dual- phase mode 5 A output. Enabled by c BCORE_MERGE. Output both inductors need to be together. | | Outputs from | | |
| MEM / IO dual-phase mode | 3 A output. Enabled by controls BUCK_MERGE. Buck outputs should share the same inductor. | | | |
| DVC_ <x> register control</x> | If VBUCK <x>_SEL_A and VBUCL<x>_SEL_B have different voltages and only one specific voltage is desired, then the regulator needs to be set correctly.</x></x> | | | |
| Output capacitors | BUCKCORE1 / BUCKCORE2: Full Current Mode: 2 x 47 μF Half Current Mode: 2 x 22 μF | | | |

Application Note

Revision 1.1

24-Feb-2022





| Bucks | Notes | Checked (Y/N) | Comments |
|--|--|------------------|----------|
| | BUCKPRO: | . , | |
| | Full Current Mode: 2 x 47 µF | | |
| | Half Current Mode: 2 x 22 µF | | |
| | BUCKPERI: | | |
| | 2 x 22 μF | | |
| | BUCKMEM: | | |
| | Full Current Mode: 2 x 47 µF | | |
| | Half Current Mode: 2 x 22 µF | | |
| | BUCKIO: | | |
| | 2 x 22 μF | | |
| GPIOs | | | |
| | Check that they are one of the following: | | |
| Unused GPIOs | configured as an input, with internal pull-down enabled via registers CONFIG_L and CONFIG_K, or, | | |
| | configured as an output, or, | | |
| | tied to GND | | |
| GPIO events | Check unused GPIOs have events masked in register IRQ_MASK_C. | | |
| Are there any GPIOs | Check the signal behavior. | | |
| configured to have special features? (SYS_EN, PWR_EN, Watchdog trigger input) | Ensure the port is correctly configured as active-high or active- low using control GPIO <x>_TYPE.</x> | | |



| Power Sequencer | Notes | Checked (Y/N) | Comments |
|--|---|------------------|----------|
| Start-up sequence | Is it correct for the system requirements? | | |
| WAIT_STEP and dummy slots Has the WAIT_STEP feature been used correctly, or set to 0x00? If dummy (empty) slots are used, are they correct? | | | |
| Turning all regulators on in the same slot will cause a large inrush current and potentially cause a drop-in input voltage and cause the PMIC to power down. | | | |
| Are the sequencer pointers placed in a suitable slot? | PART_DOWN ≤ SYSTEM_END SYSTEM_END ≤ POWER_END POWER_END ≤ MAX_COUNT | | |

Note 1 2 x 1 μF shared by all VDD_LDOx pins if they are all close together, for example, all attached to a power/split plane.

Note 2 $22 \ \mu\text{F}$ within 1.5 mm of each BUCKCORE1, BUCKCORE2 and BUCKPRO supply pin.

Note 3 10µF within 1.5 mm of each BUCKPERI, BUCKIO and BUCKMEM supply pin or 1 x 22µF if all are attached to a PCB power/split plane

5 Further Assistance

For further assistance on debugging and for a detailed schematic and OTP check, please refer to the DA9063L Datasheet found on the Dialog website (https://www.dialog-semiconductor.com/pmics) or contact your local FAE.



Revision History

| Revision | Date | Description |
|----------|-------------|--|
| 1.0 | 16-Nov-2017 | Initial version. |
| 1.1 | 24-Feb-2022 | File was rebranded with new logo, copyright and disclaimer |

Application Note





Status Definitions

| Status | Definition |
|-------------------------|--|
| DRAFT | The content of this document is under review and subject to formal approval, which may result in modifications or additions. |
| APPROVED or unmarked | The content of this document has been approved for publication. |

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